

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently amended) An encapsulation for an organic electronic component arranged on a substrate, wherein the component is encapsulated in a dimensionally stable capsule attached to the substrate by glue comprising absorbents, and a protective film covers the component at least in an area of transition from the capsule to the substrate, the protective film consisting of a material that is not adhesive and the protective film being more insulating against moisture and/or oxygen than ~~the glue used for gluing the capsule to the substrate~~ an adhesive, at least partially loaded with an adsorbent for moisture and/or oxygen, for gluing an organic electronic component to a substrate.

2. (Canceled)

3. (Previously presented) The encapsulation as in claim 1, wherein the entire exterior of the component is covered with a protective film.

4. (Previously presented) The encapsulation as in claim 1, wherein said protective film includes at least one thin-barrier film.

5. (Previously presented) The encapsulation as in claim 1, wherein said protective film includes a film made of silicon nitride.

6. (Withdrawn) The encapsulation as in claim 1, wherein said protective film includes a layer made of parylene C.

7. (Previously presented) The encapsulation as in claim 1, wherein said protective film has a thickness in the range of 1 nm to 500 μm .

8. (Withdrawn) A method for producing an encapsulation, wherein an organic electronic component on a substrate is first covered with a capsule, the capsule is then fixed to the substrate, and the encapsulated component is thereafter covered at least in part with a protective film.

9. (Withdrawn) The method as in claim 8, wherein said capsule is glued to said substrate.

10. (Withdrawn) The method as in claim 8, wherein said protective film is applied to said encapsulated component by a method selected from the group including the following methods:

chemical vapor deposition, physical vapor deposition, wet chemical deposition, such as spin coating, dip coating, drop coating, printing techniques such as stencil printing, squeegee printing, screen printing, ink jet processes, spraying, plasma coating methods, plasma polymerization methods, laminating processes, hot sealing, transfer techniques (such as thermotransfer), welding methods and injection molding.

11. (Withdrawn) The method as in claim 8, wherein the application of the protective film takes place at least in part under reduced pressure.

12. (Withdrawn – currently amended) The method as in claim 8, wherein the application of the protective film takes place at least in part in a high vacuum or at least in part via chemical vapor deposition.

13. (Withdrawn) The method as in claim 12, wherein said chemical vapor deposition is plasma-assisted.

14. (Withdrawn) The method as in claim 8, wherein the contacting of the component by means of, inter alia, a connection cable bringing said organic electronic component into contact with an external drive or playback electronics and/or another type of connection (grounding) takes place prior to the application of said thin-barrier film protective film.

15. (Withdrawn) The use of an encapsulation according to claim 1 to protect organic electronic components, such as organic light-emitting diodes, polymer chips and/or organic photovoltaic and/or electrochromic elements and/or display applications that are organically based.

16. (Currently amended) An encapsulation for an organic electronic component arranged on a substrate, the encapsulation comprising:

the component encapsulated in a dimensionally stable capsule attached to the substrate by glue; and

a protective film covering the component at least in an area of transition from the capsule to the substrate, the capsule comprising horizontal and lateral areas with respect to the component, wherein the lateral areas protrude from the layer formed by the horizontal areas and the glue is arranged between the lateral areas of the capsule and the substrate.

17. (New) The encapsulation as in claim 16, wherein the entire exterior of the component is covered with a protective film.

18. (New) The encapsulation as in claim 16, wherein said protective film includes at least one thin-barrier film.

19. (New) The encapsulation as in claim 16, wherein said protective film includes a film made of silicon nitride.

20. (New) The encapsulation as in claim 16, wherein said protective film has a thickness in the range of 1 nm to 500 μm .